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DB=U	ISPT; PLUR=YES; OP=ADJ		
<u>L3</u>	L2 and trench	7	<u>L3</u>
<u>L2</u>	L1 and (polysilicon near2 fill)	7	<u>L.2</u>
<u>L1</u>	jfet and mosfet	1343	<u>L1</u>

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Search Results - Record(s) 1 through 7 of 7 returned.

1. Document ID: US 6707095 B1

L3: Entry 1 of 7

File: USPT

Mar 16, 2004

US-PAT-NO: 6707095

DOCUMENT-IDENTIFIER: US 6707095 B1

TITLE: Structure and method for improved vertical MOSFET DRAM cell-to-cell

isolation

Claims KWC Draw Do Full Title Citation Front Review Classification Date Reference 2. Document ID: US 6576516 B1 Jun 10, 2003 L3: Entry 2 of 7 File: USPT

US-PAT-NO: 6576516

DOCUMENT-IDENTIFIER: US 6576516 B1

TITLE: High voltage power MOSFET having a voltage sustaining region that includes doped columns formed by $\underline{\text{trench}}$ etching and diffusion from regions of oppositely

doped polysilicon

Full Title Citation Front Review Classification Data Reference 3. Document ID: US 6441422 B1 Aug 27, 2002 L3: Entry 3 of 7 File: USPT

US-PAT-NO: 6441422

DOCUMENT-IDENTIFIER: US 6441422 B1

TITLE: Structure and method for ultra-scalable hybrid DRAM cell with contacted P-

well

Full Title Citation Front Review Classification Date Reference Claims Killic Draw Di 4. Document ID: US 6291298 B1

L3: Entry 4 of 7

File: USPT

Sep 18, 2001

US-PAT-NO: 6291298

Record List Display Page 2 of 3

DOCUMENT-IDENTIFIER: US 6291298 B1

TITLE: Process of manufacturing Trench gate semiconductor device having gate oxide

layer with multiple thicknesses

Full | Title | Citation | Front | Review | Classification | Date | Reference | Section | Section | Claims | RMC | Draw Do

5. Document ID: US 6284593 B1

L3: Entry 5 of 7

File: USPT

Sep 4, 2001

US-PAT-NO: 6284593

DOCUMENT-IDENTIFIER: US 6284593 B1

TITLE: Method for shallow trench isolated, contacted well, vertical MOSFET DRAM

Full Title Citation Front Review Classification Date Reference Claims NAC Draw Do

6. Document ID: US 6121089 A

L3: Entry 6 of 7

File: USPT

Sep 19, 2000

US-PAT-NO: 6121089

DOCUMENT-IDENTIFIER: US 6121089 A

TITLE: Methods of forming power semiconductor devices having merged split-well body

regions therein

Full Title Citation Front Review Classification Date Reference Claims KWC Draw De

7. Document ID: US 6078090 A

L3: Entry 7 of 7

File: USPT

Jun 20, 2000

US-PAT-NO: 6078090

DOCUMENT-IDENTIFIER: US 6078090 A

TITLE: Trench-gated Schottky diode with integral clamping diode

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Terms Documents

L2 and trench 7

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